

Model Name: EBA27001-10

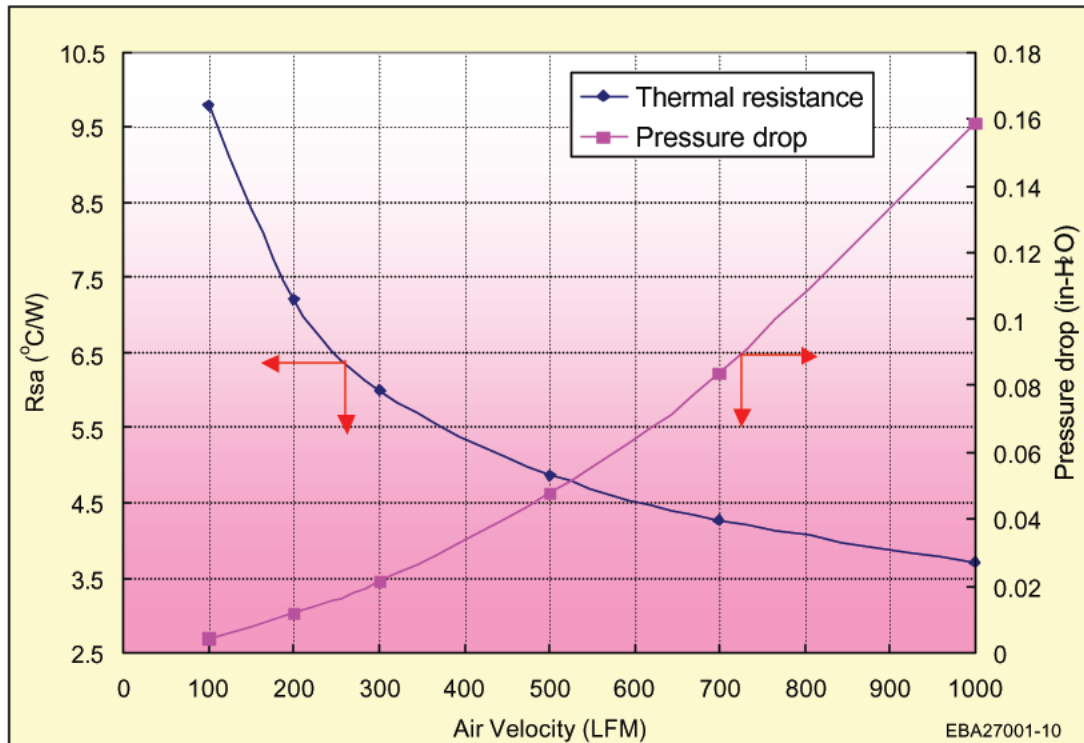
BGA Heat Sink For 27x27 Chip set

*Specification:

1. Material: Aluminum 6063
2. Weight: 8 gm
3. Technology: Extrusion
4. Finish: Black Anodize
5. Heat Sink Dimension:
26.4*26.4*9.8mm
6. Copper package and Moulding
compound package available
7. Heat Source size: Uniform



*Performance Data:



AMERICAN THERMAL PRODUCTS

Medland & Associates, Inc.

Tel: 408-686-0460

Fax: 408-686-0462

Email: sales@medlandandassociates.com

www.medlandandassociates.com